

**RADIATION HARDENED  
LOGIC LEVEL POWER MOSFET  
SURFACE MOUNT (UB)**

**IRHLUB770Z4  
60V, N-CHANNEL**  
 **TECHNOLOGY**

**Product Summary**

| Part Number | Radiation Level | RDS(on) | ID   |
|-------------|-----------------|---------|------|
| IRHLUB770Z4 | 100K Rads (Si)  | 0.55Ω   | 0.8A |
| IRHLUB730Z4 | 300K Rads (Si)  | 0.55Ω   | 0.8A |
| IRHLUB740Z4 | 600K Rads (Si)  | 0.55Ω   | 0.8A |
| IRHLUB780Z4 | 1000K Rads (Si) | 0.55Ω   | 0.8A |



International Rectifier's R7™ Logic Level Power MOSFETs provide simple solution to interfacing CMOS and TTL control circuits to power devices in space and other radiation environments. The threshold voltage remains within acceptable operating limits over the full operating temperature and post radiation. This is achieved while maintaining single event gate rupture and single event burnout immunity.

These devices are used in applications such as current boost low signal source in PWM, voltage comparator and operational amplifiers.

**Features:**

- 5V CMOS and TTL Compatible
- Fast Switching
- Single Event Effect (SEE) Hardened
- Low Total Gate Charge
- Simple Drive Requirements
- Ease of Paralleling
- Hermetically Sealed
- Light Weight
- Complimentary P-Channel Available - IRHLUB7970Z4

**Absolute Maximum Ratings**

**Pre-Irradiation**

|                             | Parameter                       |              | Units |
|-----------------------------|---------------------------------|--------------|-------|
| ID @ VGS = 4.5V, TC = 25°C  | Continuous Drain Current        | 0.8          | A     |
| ID @ VGS = 4.5V, TC = 100°C | Continuous Drain Current        | 0.5          |       |
| IDM                         | Pulsed Drain Current ①          | 3.2          |       |
| PD @ TC = 25°C              | Max. Power Dissipation          | 0.6          | W     |
|                             | Linear Derating Factor          | 0.0045       | W/°C  |
| VGS                         | Gate-to-Source Voltage          | ±10          | V     |
| EAS                         | Single Pulse Avalanche Energy ② | 2.0          | mJ    |
| IAR                         | Avalanche Current ①             | 0.8          | A     |
| EAR                         | Repetitive Avalanche Energy ①   | 0.06         | mJ    |
| dv/dt                       | Peak Diode Recovery dv/dt ③     | 4.0          | V/ns  |
| TJ                          | Operating Junction              | -55 to 150   | °C    |
| TSTG                        | Storage Temperature Range       |              |       |
|                             | Lead Temperature                | 300 (for 5s) |       |
|                             | Weight                          | 43 (Typical) | mg    |

For footnotes refer to the last page

**Electrical Characteristics @ T<sub>j</sub> = 25°C (Unless Otherwise Specified)**

|                                     | Parameter                                    | Min  | Typ  | Max  | Units | Test Conditions                                                                            |
|-------------------------------------|----------------------------------------------|------|------|------|-------|--------------------------------------------------------------------------------------------|
| BV <sub>DSS</sub>                   | Drain-to-Source Breakdown Voltage            | 60   | —    | —    | V     | V <sub>GS</sub> = 0V, I <sub>D</sub> = 250μA                                               |
| ΔBV <sub>DSS</sub> /ΔT <sub>j</sub> | Temperature Coefficient of Breakdown Voltage | —    | 0.07 | —    | V/°C  | Reference to 25°C, I <sub>D</sub> = 1.0mA                                                  |
| R <sub>DS(on)</sub>                 | Static Drain-to-Source On-State Resistance   | —    | —    | 0.55 | Ω     | V <sub>GS</sub> = 4.5V, I <sub>D</sub> = 0.5A ④                                            |
| V <sub>GS(th)</sub>                 | Gate Threshold Voltage                       | 1.0  | —    | 2.0  | V     | V <sub>DS</sub> = V <sub>GS</sub> , I <sub>D</sub> = 250μA                                 |
| g <sub>fs</sub>                     | Forward Transconductance                     | 0.23 | —    | —    | S (Ω) | V <sub>DS</sub> = 10V, I <sub>DS</sub> = 0.5A ④                                            |
| I <sub>DSS</sub>                    | Zero Gate Voltage Drain Current              | —    | —    | 1.0  | μA    | V <sub>DS</sub> = 48V, V <sub>GS</sub> = 0V                                                |
|                                     |                                              | —    | —    | 10   |       | V <sub>DS</sub> = 48V, V <sub>GS</sub> = 0V, T <sub>j</sub> = 125°C                        |
| I <sub>GSS</sub>                    | Gate-to-Source Leakage Forward               | —    | —    | 100  | nA    | V <sub>GS</sub> = 10V                                                                      |
| I <sub>GSS</sub>                    | Gate-to-Source Leakage Reverse               | —    | —    | -100 |       | V <sub>GS</sub> = -10V                                                                     |
| Q <sub>g</sub>                      | Total Gate Charge                            | —    | —    | 3.6  | nC    | V <sub>GS</sub> = 4.5V, I <sub>D</sub> = 0.8A                                              |
| Q <sub>gs</sub>                     | Gate-to-Source Charge                        | —    | —    | 1.5  |       | V <sub>DS</sub> = 30V                                                                      |
| Q <sub>gd</sub>                     | Gate-to-Drain ('Miller') Charge              | —    | —    | 1.8  |       |                                                                                            |
| t <sub>d(on)</sub>                  | Turn-On Delay Time                           | —    | —    | 8.0  | ns    | V <sub>DD</sub> = 30V, I <sub>D</sub> = 0.8A, V <sub>GS</sub> = 4.5V, R <sub>G</sub> = 24Ω |
| t <sub>r</sub>                      | Rise Time                                    | —    | —    | 10   |       |                                                                                            |
| t <sub>d(off)</sub>                 | Turn-Off Delay Time                          | —    | —    | 26   |       |                                                                                            |
| t <sub>f</sub>                      | Fall Time                                    | —    | —    | 10   |       |                                                                                            |
| L <sub>S</sub> + L <sub>D</sub>     | Total Inductance                             | —    | 8.4  | —    | nH    | Measured from the center of drain pad to center of source pad                              |
| C <sub>iss</sub>                    | Input Capacitance                            | —    | 166  | —    | pF    | V <sub>GS</sub> = 0V, V <sub>DS</sub> = 25V                                                |
| C <sub>oss</sub>                    | Output Capacitance                           | —    | 42   | —    |       | f = 1.0MHz                                                                                 |
| C <sub>rss</sub>                    | Reverse Transfer Capacitance                 | —    | 3.5  | —    |       |                                                                                            |
| R <sub>g</sub>                      | Gate Resistance                              | —    | 12   | —    | Ω     | f = 5.0MHz, open drain                                                                     |

**Source-Drain Diode Ratings and Characteristics**

|                 | Parameter                              | Min                                                                                                                  | Typ | Max | Units | Test Conditions                                                      |
|-----------------|----------------------------------------|----------------------------------------------------------------------------------------------------------------------|-----|-----|-------|----------------------------------------------------------------------|
| I <sub>S</sub>  | Continuous Source Current (Body Diode) | —                                                                                                                    | —   | 0.8 | A     |                                                                      |
| I <sub>SM</sub> | Pulse Source Current (Body Diode) ①    | —                                                                                                                    | —   | 3.2 |       |                                                                      |
| V <sub>SD</sub> | Diode Forward Voltage                  | —                                                                                                                    | —   | 1.2 | V     | T <sub>j</sub> = 25°C, I <sub>S</sub> = 0.8A, V <sub>GS</sub> = 0V ④ |
| t <sub>rr</sub> | Reverse Recovery Time                  | —                                                                                                                    | —   | 70  | ns    | T <sub>j</sub> = 25°C, I <sub>F</sub> = 0.8A, di/dt ≤ 100A/μs        |
| Q <sub>RR</sub> | Reverse Recovery Charge                | —                                                                                                                    | —   | 75  | nC    | V <sub>DD</sub> ≤ 25V ④                                              |
| t <sub>on</sub> | Forward Turn-On Time                   | Intrinsic turn-on time is negligible. Turn-on speed is substantially controlled by L <sub>S</sub> + L <sub>D</sub> . |     |     |       |                                                                      |

**Thermal Resistance**

|                   | Parameter        | Min | Typ | Max | Units | Test Conditions |
|-------------------|------------------|-----|-----|-----|-------|-----------------|
| R <sub>thJA</sub> | Junction-to-Case | —   | —   | 220 | °C/W  |                 |

Note: Corresponding Spice and Saber models are available on International Rectifier Web site.

For footnotes refer to the last page

## Radiation Characteristics

## IRHLUB770Z4

International Rectifier Radiation Hardened MOSFETs are tested to verify their radiation hardness capability. The hardness assurance program at International Rectifier is comprised of two radiation environments. Every manufacturing lot is tested for total ionizing dose (per notes 5 and 6) using the TO-3 package. Both pre- and post-irradiation performance are tested and specified using the same drive circuitry and test conditions in order to provide a direct comparison.

**Table 1. Electrical Characteristics @ Tj = 25°C, Post Total Dose Irradiation ⑤⑥**

|                     | Parameter                                               | Up to 600K Rads(Si) <sup>1</sup> |      | 1000K Rads(Si) <sup>2</sup> |      | Units | Test Conditions                                            |
|---------------------|---------------------------------------------------------|----------------------------------|------|-----------------------------|------|-------|------------------------------------------------------------|
|                     |                                                         | Min                              | Max  | Min                         | Max  |       |                                                            |
| BV <sub>DSS</sub>   | Drain-to-Source Breakdown Voltage                       | 60                               | —    | 60                          | —    | V     | V <sub>GS</sub> = 0V, I <sub>D</sub> = 250μA               |
| V <sub>GS(th)</sub> | Gate Threshold Voltage                                  | 1.0                              | 2.0  | 1.0                         | 2.0  |       | V <sub>GS</sub> = V <sub>DS</sub> , I <sub>D</sub> = 250μA |
| I <sub>GSS</sub>    | Gate-to-Source Leakage Forward                          | —                                | 100  | —                           | 100  | nA    | V <sub>GS</sub> = 10V                                      |
| I <sub>GSS</sub>    | Gate-to-Source Leakage Reverse                          | —                                | -100 | —                           | -100 |       | V <sub>GS</sub> = -10V                                     |
| I <sub>DSS</sub>    | Zero Gate Voltage Drain Current                         | —                                | 1.0  | —                           | 10   | μA    | V <sub>DS</sub> = 48V, V <sub>GS</sub> = 0V                |
| R <sub>DS(on)</sub> | Static Drain-to-Source ④<br>On-State Resistance (TO-39) | —                                | 0.55 | —                           | 0.55 | Ω     | V <sub>GS</sub> = 4.5V, I <sub>D</sub> = 0.5A              |
| R <sub>DS(on)</sub> | Static Drain-to-Source ④<br>On-State Resistance (UB)    | —                                | 0.55 | —                           | 0.55 | Ω     | V <sub>GS</sub> = 4.5V, I <sub>D</sub> = 0.5A              |
| V <sub>SD</sub>     | Diode Forward Voltage ④                                 | —                                | 1.2  | —                           | 1.2  | V     | V <sub>GS</sub> = 0V, I <sub>S</sub> = 0.8A                |

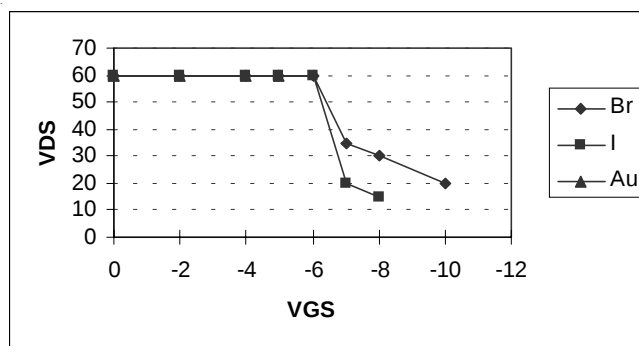
1. Part numbers IRHLUB770Z4, IRHLUB730Z4, IRHLUB740Z4

2. Part number IRHLUB780Z4

International Rectifier radiation hardened MOSFETs have been characterized in heavy ion environment for Single Event Effects (SEE). Single Event Effects characterization is illustrated in Fig. a and Table 2.

**Table 2. Single Event Effect Safe Operating Area**

| Ion | LET<br>(MeV/(mg/cm <sup>2</sup> )) | Energy<br>(MeV) | Range<br>(μm) | V <sub>DS</sub> (V)      |                           |                           |                           |                           |                           |                           |                            |
|-----|------------------------------------|-----------------|---------------|--------------------------|---------------------------|---------------------------|---------------------------|---------------------------|---------------------------|---------------------------|----------------------------|
|     |                                    |                 |               | @V <sub>GS</sub> =<br>0V | @V <sub>GS</sub> =<br>-2V | @V <sub>GS</sub> =<br>-4V | @V <sub>GS</sub> =<br>-5V | @V <sub>GS</sub> =<br>-6V | @V <sub>GS</sub> =<br>-7V | @V <sub>GS</sub> =<br>-8V | @V <sub>GS</sub> =<br>-10V |
| Br  | 37.3                               | 285             | 36.8          | 60                       | 60                        | 60                        | 60                        | 60                        | 35                        | 30                        | 20                         |
| I   | 59.9                               | 345             | 32.7          | 60                       | 60                        | 60                        | 60                        | 60                        | 20                        | 15                        | -                          |
| Au  | 82.3                               | 357             | 28.5          | 60                       | 60                        | 60                        | 60                        | -                         | -                         | -                         | -                          |



**Fig a. Single Event Effect, Safe Operating Area**

For footnotes refer to the last page

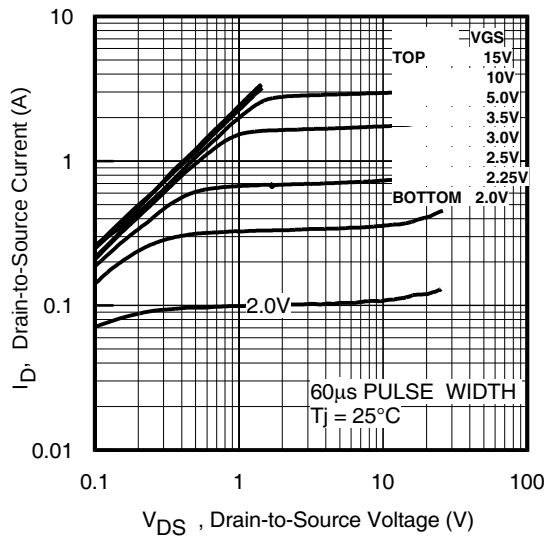


Fig 1. Typical Output Characteristics

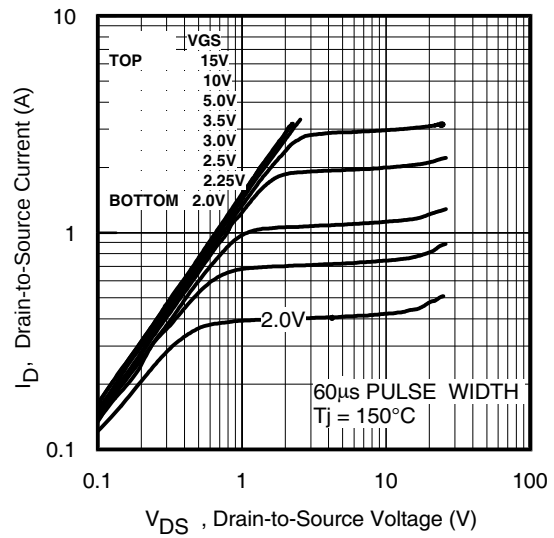


Fig 2. Typical Output Characteristics

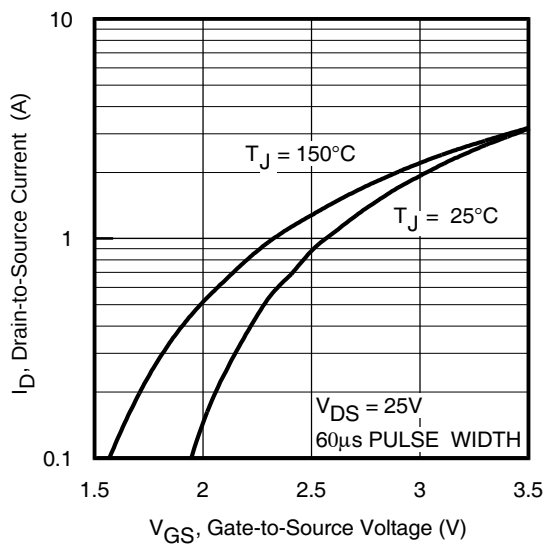


Fig 3. Typical Transfer Characteristics

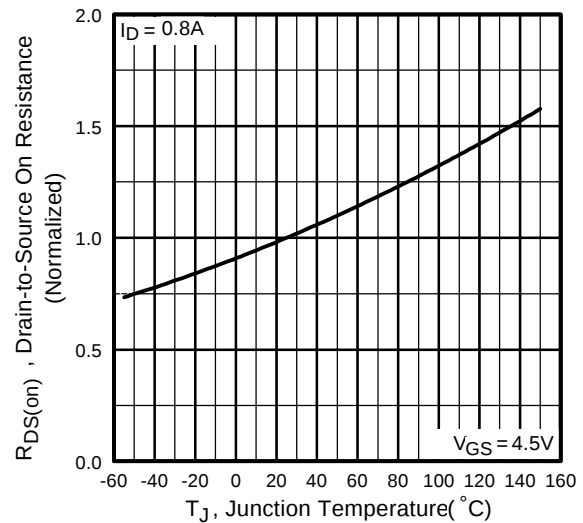
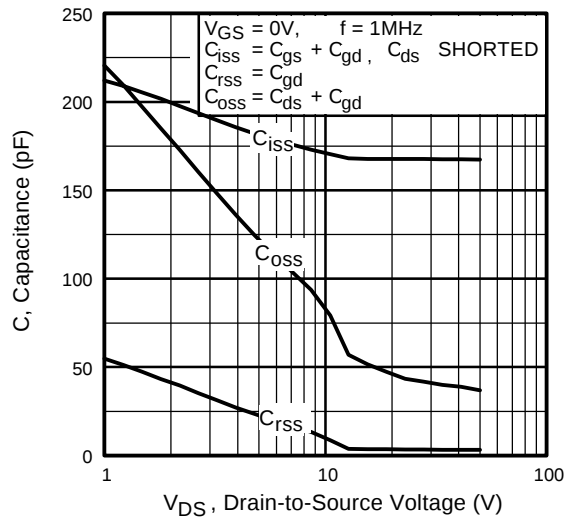
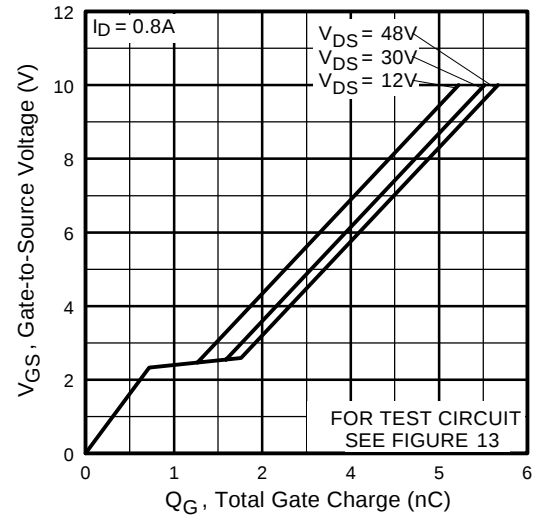


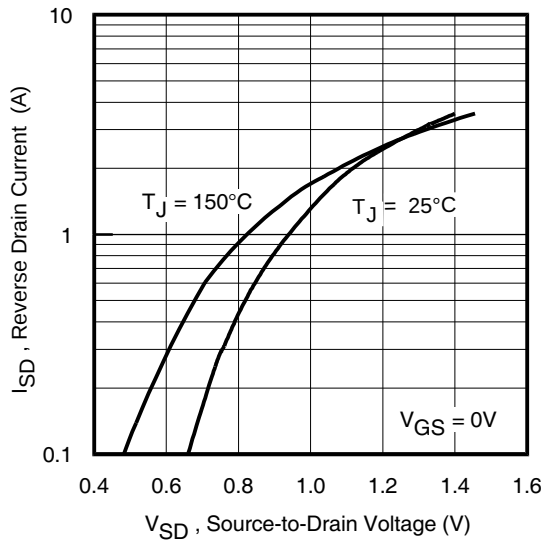
Fig 4. Normalized On-Resistance Vs. Temperature



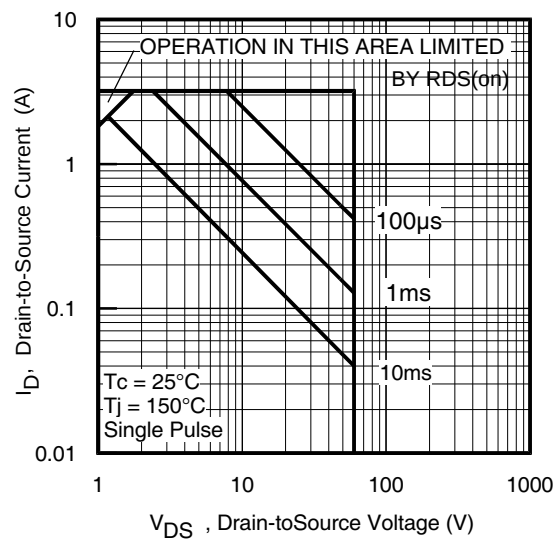
**Fig 5.** Typical Capacitance Vs. Drain-to-Source Voltage



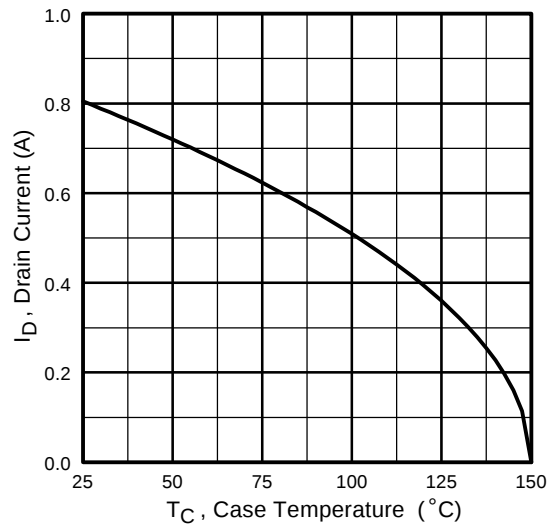
**Fig 6.** Typical Gate Charge Vs. Gate-to-Source Voltage



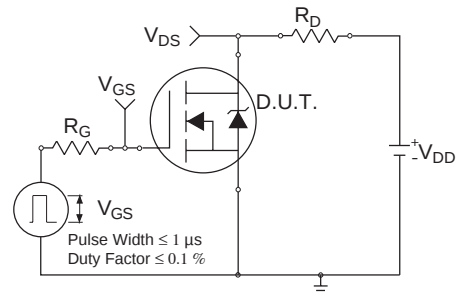
**Fig 7.** Typical Source-Drain Diode Forward Voltage



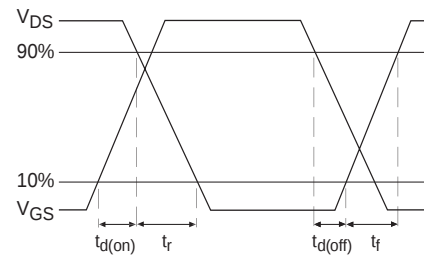
**Fig 8.** Maximum Safe Operating Area



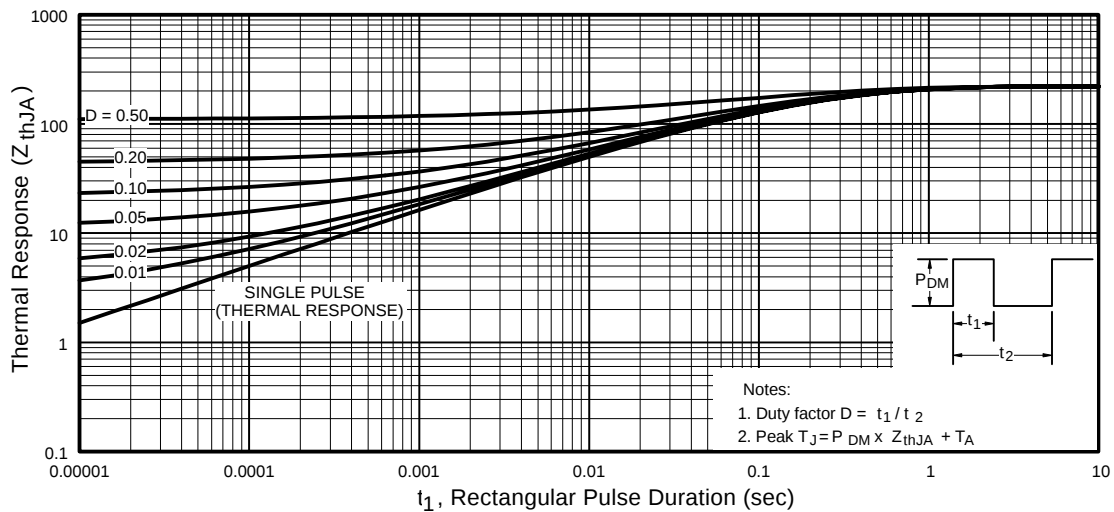
**Fig 9.** Maximum Drain Current Vs. Case Temperature



**Fig 10a.** Switching Time Test Circuit



**Fig 10b.** Switching Time Waveforms



**Fig 11.** Maximum Effective Transient Thermal Impedance, Junction-to-Ambient

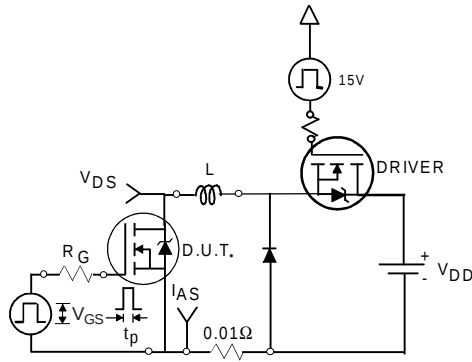


Fig 12a. Unclamped Inductive Test Circuit

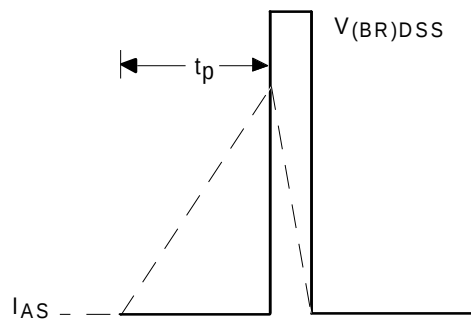


Fig 12b. Unclamped Inductive Waveforms

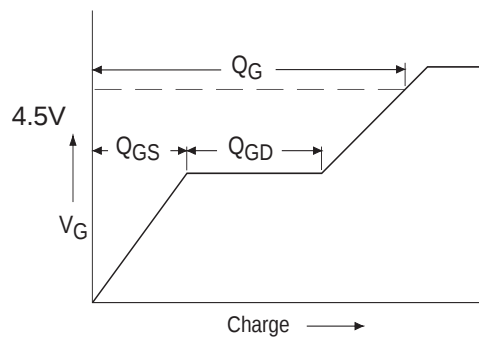


Fig 13a. Basic Gate Charge Waveform

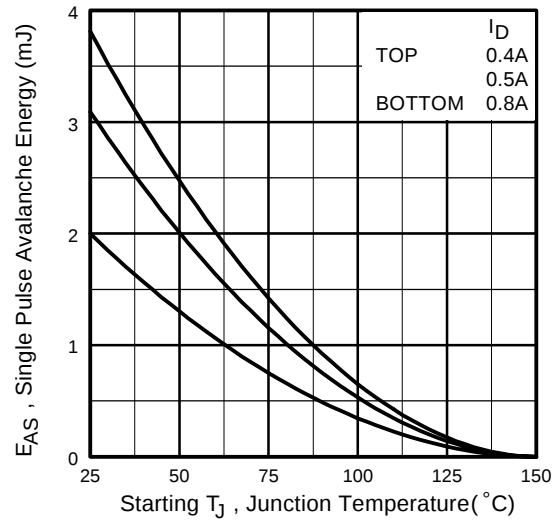


Fig 12c. Maximum Avalanche Energy Vs. Drain Current

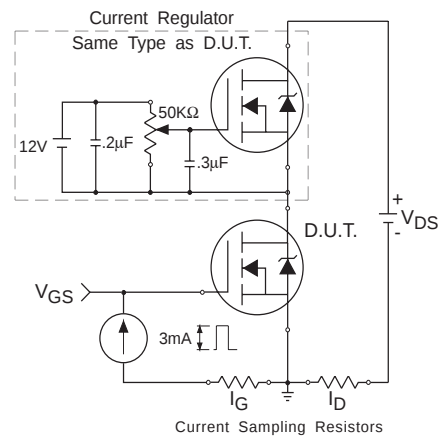
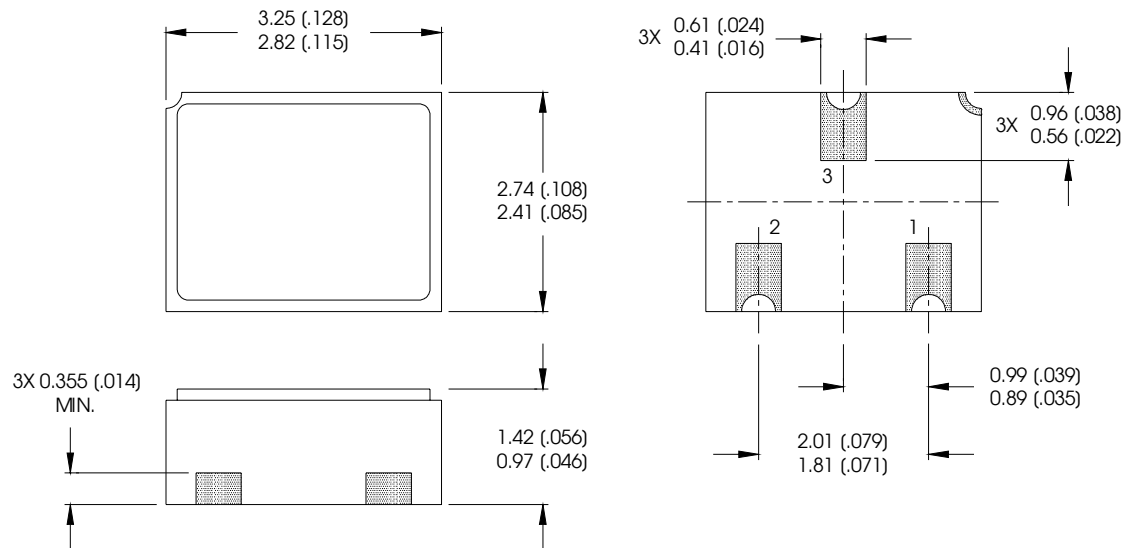


Fig 13b. Gate Charge Test Circuit

**Footnotes:**

- ① Repetitive Rating; Pulse width limited by maximum junction temperature.
- ②  $V_{DD} = 25V$ , starting  $T_J = 25^\circ C$ ,  $L = 6.3\text{ mH}$   
Peak  $I_L = 0.8A$ ,  $V_{GS} = 10V$
- ③  $I_{SD} \leq 0.8A$ ,  $di/dt \leq 130A/\mu s$ ,  
 $V_{DD} \leq 60V$ ,  $T_J \leq 150^\circ C$
- ④ Pulse width  $\leq 300\text{ }\mu s$ ; Duty Cycle  $\leq 2\%$
- ⑤ **Total Dose Irradiation with  $V_{GS}$  Bias.**  
10 volt  $V_{GS}$  applied and  $V_{DS} = 0$  during irradiation per MIL-STD-750, method 1019, condition A.
- ⑥ **Total Dose Irradiation with  $V_{DS}$  Bias.**  
48 volt  $V_{DS}$  applied and  $V_{GS} = 0$  during irradiation per MIL-STD-750, method 1019, condition A.

**Case Outline and Dimensions — UB****NOTES:**

- 1. OUTLINE CONFORMS TO MIL-PRF-19500/255L
- 2. ALL DIMENSIONS ARE SHOWN IN MILLIMETERS (INCHES).
- 3. CONTROLLING DIMENSION: INCH.

**PAD ASSIGNMENTS**

- 1 = GATE
- 2 = SOURCE
- 3 = DRAIN

International  
**IR** Rectifier

**IR WORLD HEADQUARTERS:** 233 Kansas St., El Segundo, California 90245, USA Tel: (310) 252-7105

**IR LEOMINSTER :** 205 Crawford St., Leominster, Massachusetts 01453, USA Tel: (978) 534-5776

TAC Fax: (310) 252-7903

Visit us at [www.irf.com](http://www.irf.com) for sales contact information.

*Data and specifications subject to change without notice. 02/2004*